



Material Content Data Sheet



Sales Product Name	TLE4470G			Issued	28. August 2013			
MA#	MA000835164							
Package	PG-DSO-20-35			Weight*	478.75 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.953	1.03	1.03	10345	10345
leadframe	inorganic material	phosphorus	7723-14-0	0.036	0.01		75	
	non noble metal	zinc	7440-66-6	0.143	0.03		299	
	non noble metal	iron	7439-89-6	2.862	0.60		5977	
wire	non noble metal	copper	7440-50-8	116.197	24.27	24.91	242711	249062
	noble metal	gold	7440-57-5	0.460	0.10	0.10	961	961
	encapsulation	organic material	carbon black	1333-86-4	0.696	0.15		1454
encapsulation	plastics	epoxy resin	-	32.022	6.69		66887	
	inorganic material	silicondioxide	60676-86-0	315.343	65.86	72.70	658688	727029
leadfinish	non noble metal	tin	7440-31-5	2.746	0.57	0.57	5736	5736
plating	noble metal	silver	7440-22-4	1.177	0.25	0.25	2458	2458
glue	plastics	epoxy resin	-	0.528	0.11		1102	
	noble metal	silver	7440-22-4	1.583	0.33	0.44	3307	4409
*deviation	< 10%			Sum in total:		100,00		1000000

Important Remarks:

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